



GaN HEMT Pulsed Power Transistor

3.1 - 3.5 GHz, 30W Peak, 500us Pulse, 10% Duty Cycle

Production V1
23 Aug 11

Features

- GaN depletion mode HEMT microwave transistor
- Common source configuration
- Broadband Class AB operation
- Thermally enhanced Cu/Mo/Cu package
- RoHS Compliant
- +50V Typical Operation
- MTTF of 114 years (Channel Temperature < 200°C)

Application

- Civilian and Military Pulsed Radar



Product Description

The MAGX-003135-030L00 is a gold metalized matched Gallium Nitride (GaN) on Silicon Carbide RF power transistor optimized for civilian and military radar pulsed applications between 3100 - 3500 MHz. Using state of the art wafer fabrication processes, these high performance transistors provide high gain, efficiency, bandwidth, ruggedness over a wide bandwidth for today's demanding application needs. The MAGX-003135-030L00 is constructed using a thermally enhanced Cu/Mo/Cu flanged ceramic package which provides excellent thermal performance. High breakdown voltages allow for reliable and stable operation in extreme mismatched load conditions unparalleled with older semiconductor technologies.

Typical RF Performance

Freq. (MHz)	Pin (W Peak)	Pout (W Peak)	Gain (dB)	Eff (%)
3100	3	40	11.2	59.3
3300	3	40	11.2	57.7
3500	3	34	10.5	51.2

Typical RF performance measured in M/A-COM RF test fixture. Devices tested in common source Class-AB configuration as follows: Vdd=50V, Idq=130mA (pulsed), F=3.1-3.5GHz, Pulse=500us, Duty=10%.

Ordering Information

MAGX-003135-030L00 30W GaN Power Transistor
MAGX-003135-SB1PPR Evaluation Fixture

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Absolute Maximum Ratings Table (1, 2, 3)

Supply Voltage (Vdd)	+65V
Supply Voltage (Vgg)	-8 to 0V
Supply Current (Id1)	3000 mA
Input Power (Pin)	+30 dBm
Absolute Max. Junction/Channel Temp	200 °C
MTTF (T _J <200°C)	114 years
Continuous Power Dissipation (Pdiss) at 85 °C	27 W
Pulsed Power Dissipation (Pavg) at 85 °C	65 W
Thermal Resistance, (T _{channel} = 200 °C) Pulsed 500uS, 10% Duty cycle	1.8 °C/W
Operating Temp	-40 to +95C
Storage Temp	-65 to +150C
Mounting Temperature	See solder reflow profile
ESD Min. - Machine Model (MM)	50 V
ESD Min. - Human Body Model (HBM)	>250 V
MSL Level	MSL1

(1) Operation of this device above any one of these parameters may cause permanent damage.

(2) Channel temperature directly affects a device's MTTF. Channel temperature should be kept as low as possible to maximize lifetime.

(3) For saturated performance it recommended that the sum of (3*Vdd + abs(Vgg)) <175

Parameter	Test Conditions	Symbol	Min	Typ	Max	Units
DC CHARACTERISTICS						
Drain-Source Leakage Current	V _{GS} = -8V, V _{DS} = 175V	I _{DS}	-	-	2.5	mA
Gate Threshold Voltage	V _{DS} = 5V, I _D = 6mA	V _{GS(th)}	-5	-3	-2	V
Forward Transconductance	V _{DS} = 5V, I _D = 1.5mA	G _M	1.0	-	-	S
DYNAMIC CHARACTERISTICS						
Input Capacitance	V _{DS} = 0v, V _{GS} = -8V, F = 1MHz	C _{ISS}	-	13.2	-	pF
Output Capacitance	V _{DS} = 50V, V _{GS} = -8V, F = 1MHz	C _{OSS}	-	5.6	-	pF
Reverse Transfer Capacitance	V _{DS} = 50V, V _{GS} = -8V, F = 1MHz	C _{RSS}	-	0.5	-	pF

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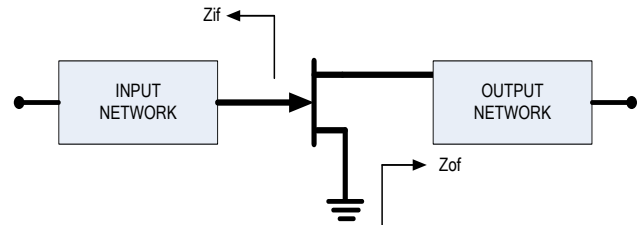
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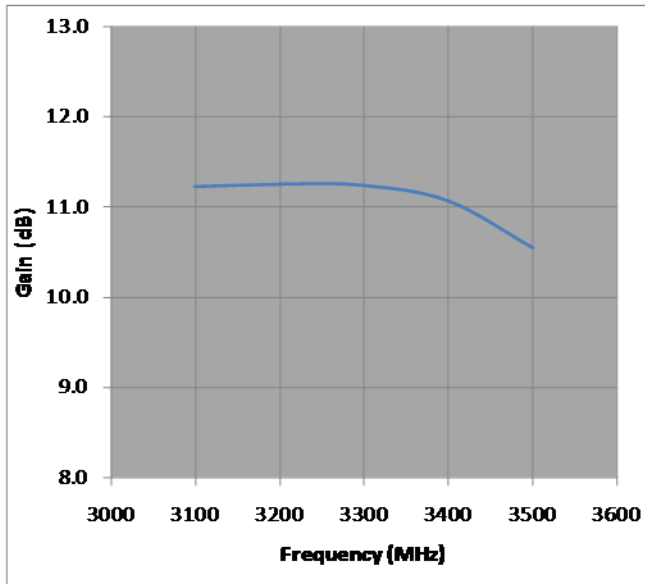
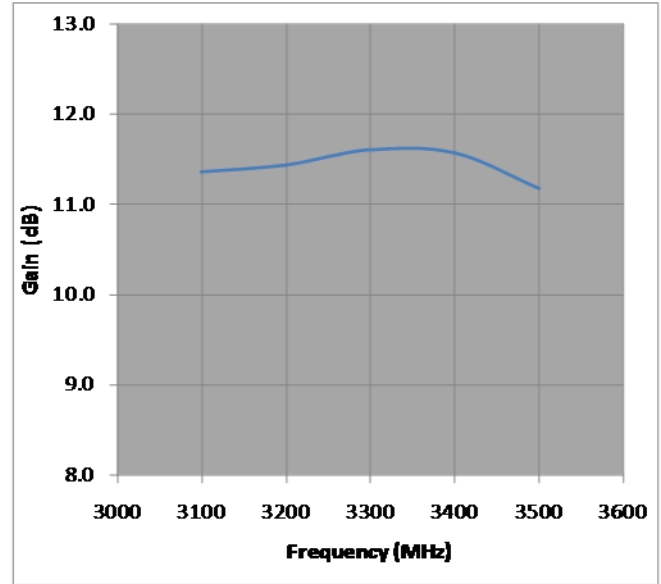
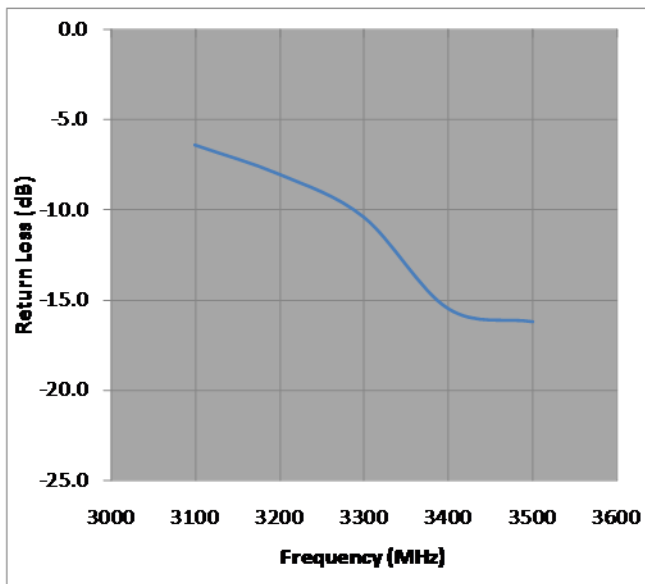
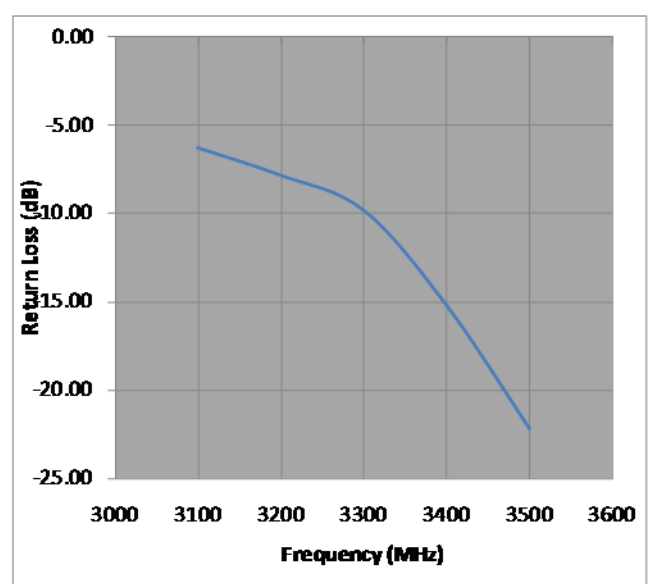
Electrical Specifications: $T_C = 25 \pm 5^\circ\text{C}$ (Room Ambient)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Units
RF FUNCTIONAL TESTS $V_{dd}=50V$, $I_{dq}=130mA$ (pulsed), $F=3.1-3.5GHz$, $Pulse=500us$, $Duty=10\%$.						
Output Power	$P_{in} = 3W$ Peak	P_{OUT}	30 3	40 4	-	W Peak W Ave
Power Gain	$P_{out} = 30W$ Peak	G_P	10.0	11.0	-	dB
Drain Efficiency	$P_{in} = 3W$ Peak	η_D	50	55	-	%
Load Mismatch Stability	$P_{in} = 3W$ Peak	VSWR-S	5:1	-		-
Load Mismatch Tolerance	$P_{in} = 3W$ Peak	VSWR-T	10:1	-		-

Test Fixture Impedance

F (MHz)	Z_{IF} (Ω)	Z_{OF} (Ω)
3100	$7.6 - j12.5$	$5.2 - j0.2$
3300	$7.5 - j11.4$	$6.0 + j0.2$
3500	$7.2 - j10.2$	$6.7 + j0.1$

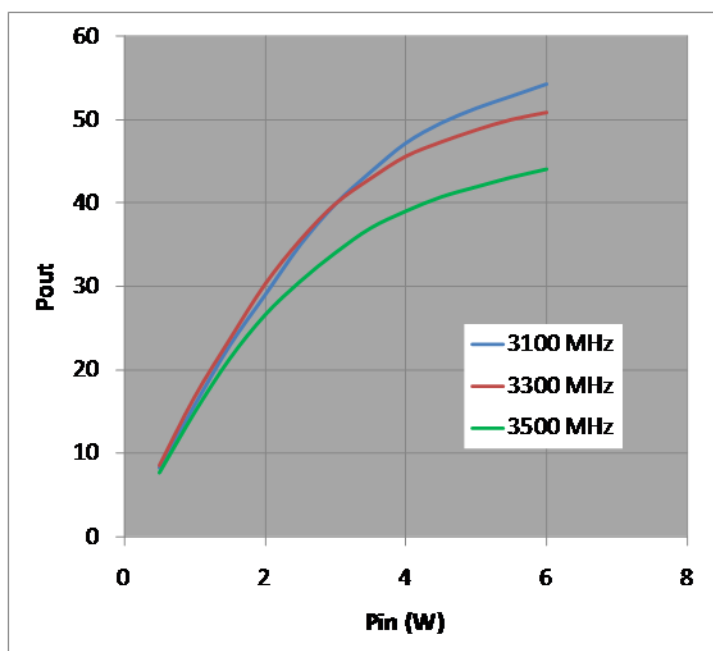


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Gain vs. Frequency
 50V Drain Bias, Idq=0.13A

Gain vs. Frequency
 65V Drain Bias, Idq=0.13A

Return Loss vs. Frequency
 50V Drain Bias, Idq=0.13A

Return Loss vs. Frequency
 65V Drain Bias, Idq=0.13A


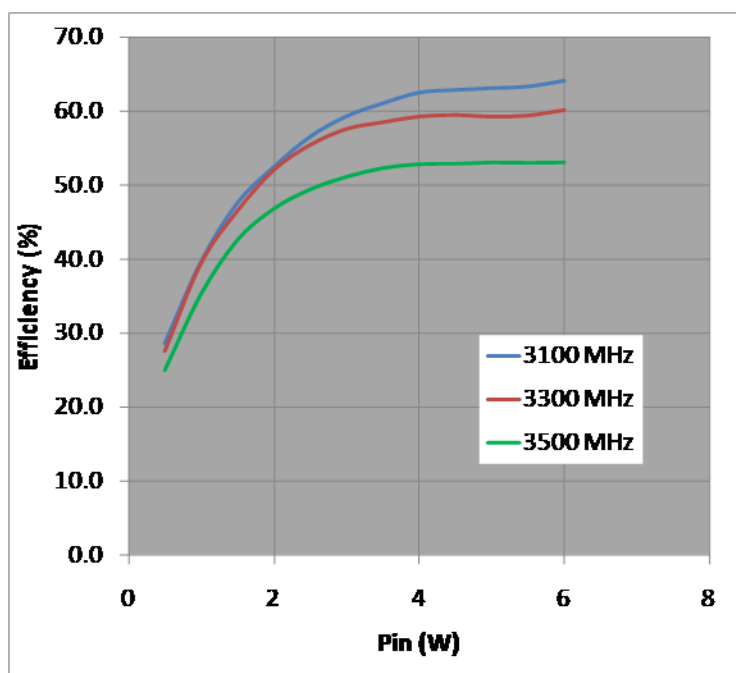
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Output Power vs. Input Power
 50V Drain Bias, $I_{dq}=0.13A$



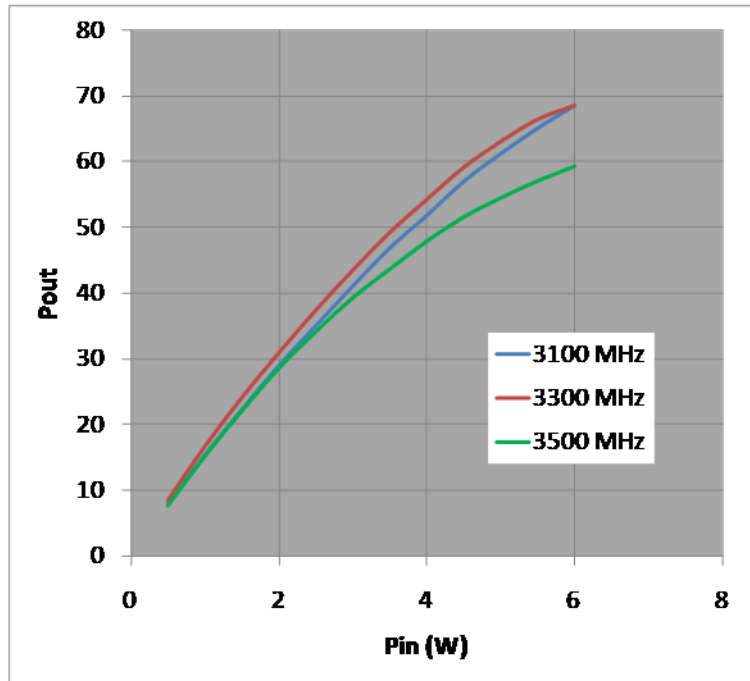
Drain Efficiency vs. Input Power
 50V Drain Bias, $I_{dq}=0.13A$



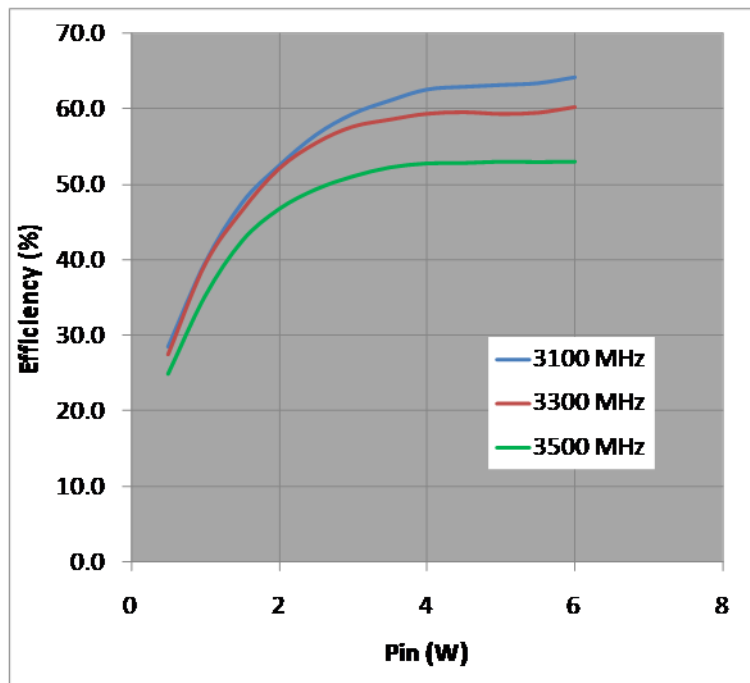
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Output Power vs. Input Power
 65V Drain Bias, $I_{dq}=0.13A$



Drain Efficiency vs. Input Power
 65V Drain Bias, $I_{dq}=0.13A$



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TFMAX-
003135-030L00

Note: A .dwg circuit drawing is available upon request

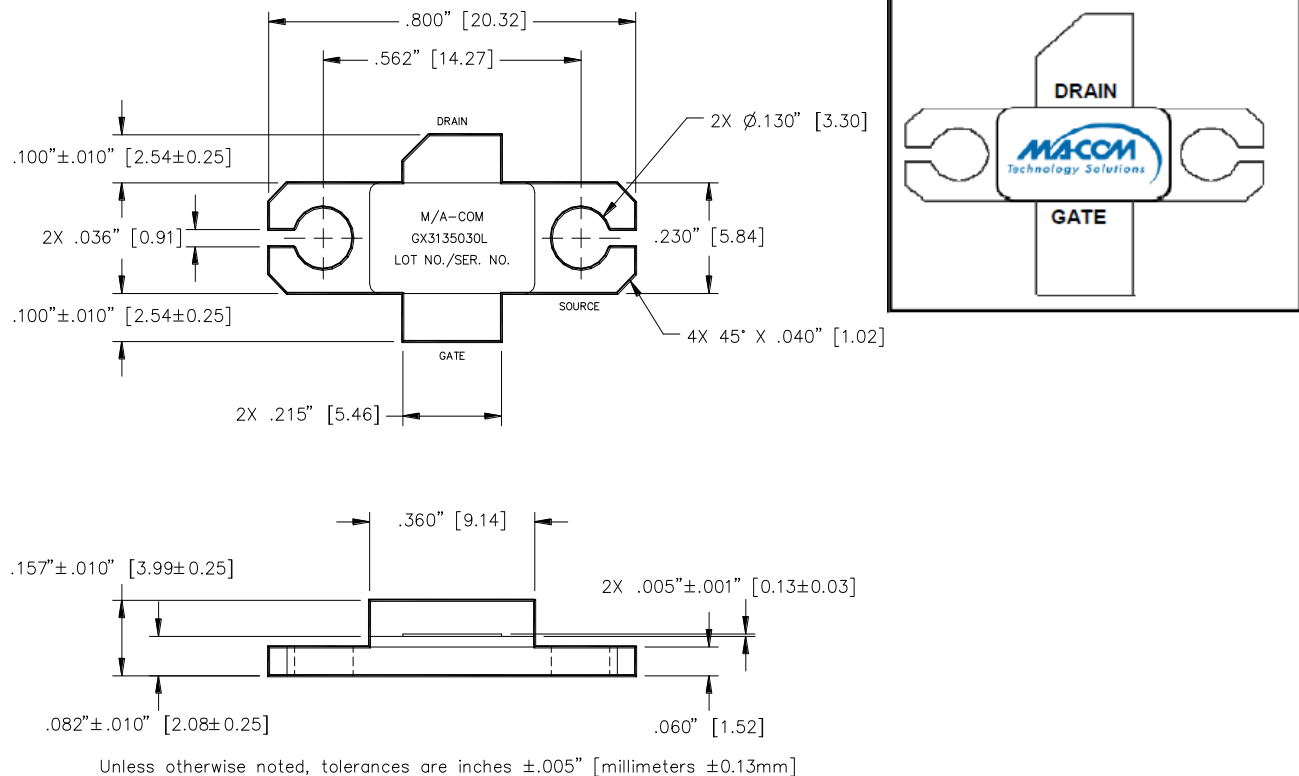
The assembly view shows the TFMAGX-003135-030L00 component mounted on a board carrier. The component is a rectangular metal package with various pins and connectors. The following components are labeled:

- CHIP CAPACITOR** 470pF 100 VOLT ATC100B471J C4,C7
- CHIP CAPACITOR** 47pF ATC100A470J (ASSEMBLY NOTE, MOUNT ON NARROW SIDE)
- PC BOARDS** ROGERS RT3006/6006 .025" THICK 1 OZ COPPER BOTH SIDES
- SMA CONNECTOR** TYCO ELECTRONICS 2052-5636-02 J1,J2
- CHIP RESISTOR** 12 OHM 1/2 WATT CR2010-2W-120J
- HEATSINK** 73050255-14
- BOARD CARRIER** 73050257-13
- TRANSISTOR CARRIER** 73050256-23
- TRANSISTOR CLAMP** 74250125-55
- FEMALE BANANA JACK** J3,J4,J5,J6
- TIN PLATED COPPER SHIM** G1-G6
- ELECTROLYTIC CAPACITOR** 100uF 6.3 VOLT
- CHIP CAPACITOR** 1uF 100 VOLT C3216X7R2A105K C9
- CHIP CAPACITOR** .1uF 100 VOLT VJ1206Y104KXBM7 C7
- CHIP CAPACITOR** 12pF ATC100A120J C1,C2,C5,C6 (ASSEMBLY NOTE, MOUNT ON NARROW SIDE)
- TFMAGX-003135-030L00**
- M/A-COM Technology Solutions**

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Outline Drawings



CORRECT DEVICE SEQUENCING

TURNING THE DEVICE ON

1. Set V_{GS} to the pinch-off (V_P), typically -5V
2. Turn on V_{DS} to nominal voltage (50V)
3. Increase V_{GS} until the I_{DS} current is reached
4. Apply RF power to desired level

TURNING THE DEVICE OFF

1. Turn the RF power off
2. Decrease V_{GS} down to V_P
3. Decrease V_{DS} down to 0V
4. Turn off V_{GS}

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